

WHAT IS CLAIMED IS:

1. A semiconductor integrated circuit device,  
comprising:

5 a plurality of I/O slots arranged in parallel  
along the peripheral portion of a chip within the inner  
region of the chip and having input/output cells  
connected thereto;

10 a plurality of pads arranged a predetermined  
distance apart from each other above said I/O slot and  
extending from the peripheral portion of the chip  
toward the central portion;

15 a plurality of first wiring each having one end  
positioned in said pad and having the other end  
positioned in the peripheral region of the inner  
portion of the chip above the I/O slot; and

a second wiring arranged in the outermost  
peripheral region of the chip and serving to connect  
the other end of each of the plural the first wiring to  
a predetermined I/O slot.

20 2. The semiconductor integrated circuit device  
according to claim 1, wherein said second wiring is  
arranged between the first wiring and the first I/O  
slot such that one end of the second wiring is  
connected to the first wiring arranged in the second  
25 I/O slot, with the other end being connected to the  
first I/O slot. ~~A~~

3. A method of connecting the wiring of a

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semiconductor integrated circuit device for connecting  
a plurality of I/O slots arranged in parallel along the  
peripheral portion of a chip within the inner region  
of the chip and having input/output cells connected  
thereto to a plurality of pads arranged a predetermined  
distance apart from each other above said I/O slot  
and extending from the peripheral portion of the chip  
toward the central portion, comprising the steps of:

connecting each of said pads to the peripheral  
portion above the I/O slot in the inner region of the  
chip; and

connecting the peripheral portion in the inner  
region of the chip to a desired I/O slot in the  
outermost peripheral region of the chip.

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